

IN THE CLAIMS:

Please amend the claims as follows:

1. (Currently Amended) A multilaser device comprising:

a first laser chip produced from a wafer lot; and

a second laser chip produced from one and the same wafer lot as that of the first laser chip;

a common back beam sensor for receiving a first back beam and a second back beam emitted from said first laser chip and said second laser chip, respectively; and  
a package containing said first laser chip, said second laser chip and said back beam sensor.

2. (Original) A multilaser device according to Claim 1, wherein a difference  $\lambda$  between oscillation wavelengths of said first laser chip and said second laser chip is  $\lambda \leq 1.5$  nm.

3. (Original) A multilaser device according to Claim 1, wherein positional accuracy  $\Delta Z$  of light emitting points of said first laser chip and said second laser chip is  $\Delta Z \leq 5 \mu\text{m}$ .

4. (Original) A multilaser device according to Claim 1, wherein said multilaser device is used in an electrophotographic apparatus and image-exposes a charged photosensitive member.